



MULTILAYER CERAMIC CAPACITORS Low Profile Series 0603 to 1210 Sizes X7R, X5R & Y5V Dielectrics RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC TT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Standard size with thin thickness.
- b. Small size with high capacitance.
- c. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

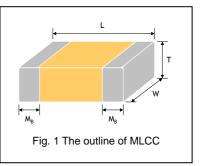
- a. For LCD panels.
- b. For PCMCA cards.
- c. For IC packaging and modules.
- d. Any thickness concerned products.

4. HOW TO ORDER

<u>11</u>	<u>31</u>	X	<u>225</u>	K	<u>100</u>	<u>C</u>	Ι
<u>Series</u>	<u>Size</u>	Dielectric	Capacitance	<u>Tolerance</u>	Rated voltage	Termination	Packaging style
TT=Low profile	18 =0603 (1608) 21 =0805 (2012) 31 =1206 (3216) 32 =1210 (3225)	X =X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point.	K=±10% M=±20% Z=-20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point.	C =Cu/Ni/Sn	T=7" reel (paper tape) P=7" reel (plastic tape)
			eg.: 225=22x10 ⁵ =2,200,000pF =2.2µF		6R3=6.3 VDC 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC		

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T ma: (mm)/Syr		M _B (mm)
0402 (1005)	1.00±0.05	0.5±0.05	0.33	L	0.25±0.10
0603 (1608)	1.6+0.15/-0.10	0.8+0.15/-0.10	0.60	Н	0.40±0.15
0805 (2012)	2.00±0.20	1.25±0.20	0.95	т	0.50±0.20
1006 (2016)	2 20 0 20	1 60 0 20	0.95	Т	0.60+0.20
1206 (3216)	3.20±0.20	1.60±0.20	1.30	J	0.60±0.20
1210 (3225)	3.20±0.30	2.50±0.20	0.95	Т	0.75±0.25



* Reflow soldering process only is recommended.



6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V			
Size	1206	0603, 0805, 1	206, 1210			
Capacitance range*	1.0µF	0.22µF to 10µF	1.0μF to 10μF			
Capacitance tolerance**	K (±10%	%), M (±20%)	Z (-20/+80%)			
Rated voltage (WVDC)	25V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V			
Tan δ*	25V: ≤10%	25V, 16V, 10V: ≤10%; 6.3V: ≤15.0%	50V: ≤7.0% 25V: ≤9.0% 16V, 10V: ≤12.5%			
Insulation resistance at Ur		RxC≥100ΩxF				
Operating temperature	-55 to +125℃	-55 to +85℃	-25 to +85℃			
Capacitance characteristic		+30/-80%				
Termination	Ni/Sn (lead-free termination)					

* Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R and at 20°C for Y5V. ** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

7. CAPACITANCE RANGE

	Dielectric	X7R		X5R													
-	Size	1206	04	0402 0603				0805				1206				1210	
Rate	ed voltage (VDC)	25	6.3	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	25
	0.22uF (224)			L	Н	Н											
	0.47uF (474)			L													
	1.0µF (105)	Т	L		Н	Н		Т	Т	Т		Т	Т	Т			
ů,	1.5µF (155)							Т	Т			Т	Т	Т			
itaı	2.2µF (225)						Т	Т	Т	Т		Т	Т	Т	Т		
ac	3.3µF (335)											Т	Т	Т		Т	
Capacitance	4.7µF (475)						Т	Т	Т			Т	Т	Т		Т	
	6.8µF (685)																
	10µF (106)						Т	Т			J	J/T					Т
	22uF (226)						Т				Т						

7-2 Y5V dielectric

	Dielectric						Y5V				
	Size	0805			1206				12	1210	
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16
	1.0µF (105)				Т						
	1.5µF (155)										
Capacitance	2.2µF (225)		Т	Т		Т	Т	Т	Т		
ital	3.3µF (335)	Т									
ac	4.7µF (475)	Т	Т			Т	Т				
Gap	6.8µF (685)					Т					
Ŭ	10µF (106)	Т				Т				Т	
	22µF (226)					J					

8. PACKAGING STYLE AND QUANTITY

Size	Thickness Max (mr	n)/Symbol	7" reel			
Size			Paper tape	Plastic tape		
0402 (1005)	0.33	L	15k	-		
0603 (1608)	0.60	Н	4k	-		
0805 (2012)	0.95	Т	4k	-		
4000 (0040)	0.95	Т	4k	-		
1206 (3216)	1.30	J	-	3k		
1210 (3225)	0.95	Т	-	3k		

Unit: pieces



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem		Test Condition			Requirem	ents		
1.	Visual and				* No remark	able defect.			
	Mechanical				* Dimension	is to conform to individual	specification sheet.		
2.	Capacitance	Cap≤10µF, 1	.0±0.2Vrms, 1kHz±10%		* Shall not e	exceed the limits given in th	ne detailed spec.		
3.	Q/ D.F.	Cap>10µF, 0	.5±0.2Vrms, 120Hz±20%		X7R/X5R		· · · · · · · · · · · · · · · · · · ·		
	(Dissipation				Rated vol	. D.F.			
	Factor)				25V, 16V,	10V ≤10%			
	,				6.3V	≤15%			
					Y5V:				
					Rated vol	. D.F.			
					50V	≤7%			
					25V	≤9%			
_					16V/10V	≤12.5%			
4.	Dielectric		ltage: 250% rated voltage.		* No eviden	ce of damage or flash over	r during test.		
	Strength	* Duration: 1							
		* Charge and	discharge current less than 50m	Α.					
5.	Insulation	To apply rate	d voltage for max. 120 sec.		≥10GΩ or R	xC≥100Ω-F whichever is s	smaller.		
	Resistance								
6.	Temperature	With no elect	rical load.						
	Coefficient	T.C.	Operating Temp		T.C.	Capacitance Change			
		X7R	-55~125℃ at 25℃	_	X7R	Within ±15%			
		X5R	-55~85℃ at 25℃	_	X5R	Within ±15%			
		Y5V	-25~85℃ at 20℃		Y5V	Within +30%/-80%			
7.	Adhesive	* Pressurizin	g force:5N (≤0603) and 10N (>0	603)	* No remark	able damage or removal o	f the terminations.		
	Strength of	* Test time: 1	0±1 sec.						
	Termination								
8.	Vibration	* Vibration fre	equency: 10~55 Hz/min.		* No remarkable damage.				
	Resistance	* Total amplit	ude: 1.5mm		* Cap change and Q/D.F.: To meet initial spec.				
		* Test time: 6	hrs. (Two hrs each in three mutu	ally					
		perpendicula	r directions.)						
9.	Solderability	* Solder temp	perature: 235±5℃		95% min. co	overage of all metalized are	ea.		
		* Dipping tim	e: 2±0.5 sec.						
10.	Bending Test	* The middle	part of substrate shall be pressur	ized by means	* No remarkable damage.				
		of the pressu	rizing rod at a rate of about 1 mm	per second until	* Cap chang	ge :			
		the deflectior	becomes 1 mm and then the pre	essure shall be	X7R/X5R:	within ±12.5%			
		maintained fo	or 5±1 sec.		Y5V: withir	ו ±30%			
		* Measureme	ent to be made after keeping at ro	om temp. for	(This capac	itance change means the	change of capacitance under		
		48±4 hrs.			specified flexure of substrate from the capacitance measured befor				
					the test.)				
11.	Resistance to	* Solder temp	perature: 260±5℃		* No remarkable damage.				
	Soldering Heat	* Dipping tim	e: 10±1 sec		* Cap change:				
		* Preheating:	120 to 150℃ for 1 minute before	imme rse the					
			a eutectic solder.		Y5V: withi	n ±20%			
			al measurement (Class II only): Pe	erform	* Q/D.F., I.R	and dielectric strength: To	o meet initial requirements.		
			for 1 hr and then set for 48±4 hrs			leaching on each edge.	,		
			ent to be made after keeping at ro	-					
		48±4 hrs. (Cl							



No.	Item		Test Condition	l	Requirements			
	Temperature Cycle	time. Step 1 2 3 4 * Before i 150+0/-10 * Measure	t the five cycles according to the Temp. (°C) Min. operating temp. +0/-3 Room temp. Max. operating temp. +3/-0 Room temp. nitial measurement (Class II onl 0°C for 1 hr and then set for 48± ement to be made after keeping	Time (min.) 30±3 2~3 30±3 2~3 2~3 y): Perform 4 hrs at r oom temp.	 * No remarkable damage. * Cap change : X7R/X5R: within ±7.5% Y5V: within ±20% * Q/D.F., I.R. and dielectric strength: To meet initial requirements. 			
13.	Humidity (Damp Heat) Steady State	* Humidit * Test tim	ıp.: 40±2℃ y: 90~95% RH e: 500+24/-0hrs. ement to be made after keeping	at room temp. for	*No remarkable damage. *Cap change : XTR/X5R: within $\pm 25\%$ Y5V: within $\pm 30\%$; 6.3V, within $\pm 30/-40\%$ *Q/D.F. value: XTR/X5R: Rated vol. D.F. 25V, 16V $\leq 15\%$ 10V $\leq 20\%$ 6.3V $\leq 30\%$ Y5V: Rated vol. D.F. 50V $\leq 10\%$ 25V $\leq 15\%$ 16V, 10V $\leq 20\%$ *I.R.: 1G Ω or RxC $\geq 10 \Omega$ -F whichever is smaller.			
14.	Humidity (Damp Heat) Load	* Humidit * Test tim * To apply	np.: 40±2℃ y: 90~95%RH e: 500+24/-0 hrs. / voltage : Rated voltage. ement to be made after keeping s.	at room temp. for	*No remarkable damage. *Cap change: X7R/X5R: within $\pm 25\%$ Y5V: within $\pm 30\%$; 6.3V, within $\pm 30/-40\%$ *Q/D.F. value: X7R/X5R: Rated vol. D.F. 25V, 16V $\leq 15\%$ 10V $\leq 20\%$ 6.3V $\leq 30\%$ Y5V: Rated vol. D.F. 50V $\leq 10\%$ 25V $\leq 15\%$ 16V, 10V $\leq 20\%$ *I.R.: 500M\Omega or RxC $\geq 5 \Omega$ -F whichever is smaller.			

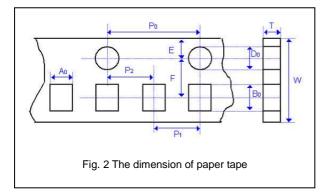


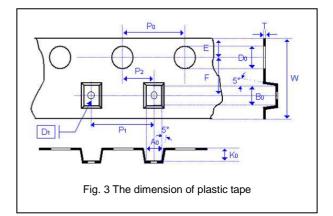
No.	ltem			Fest Conditio	n		Requirements		
15.	5. High * Test temp. : NP0, X7R/X7E: 125±3℃ Temperature NP0, X7R/X7E: 125±3℃ Load * Test time: 1000+24/-0 hrs. (Endurance) * To apply voltage: 150% of rated voltage.				No remarkable damage. *Cap change: X7R/X5R: within ±25% Y5V: within ±30%; 6.3V, within +30/-40% *Q/D.F. value: X7R/X5R:				
		Size 0603 0805 1206	Dielectric Y5V Y5V Y5V	Rated voltage 6.3V,10V 6.3V 6.3V	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$	Rated vol. 25V, 16V 10V 6.3V Y5V:	D.F. ≤15% ≤20% ≤30%		
	* Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).				Rated vol. 50V 25V 16V, 10V	D.F. ≤10% ≤15% ≤20% xC≥10 Ω-F whichever is smaller.			



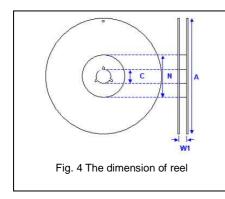
APPENDIXES

Tape & reel dimensions





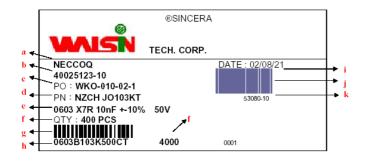
Size	06	03	0805	12	06	1210
Thickness	N	Н	т	Т	J	Т
Ao	0.62±0.05	1.10±0.10	1.50±0.10	2.00±0.10	<1.85	<2.97
Bo	1.12±0.05	1.90±0.10	2.30±0.10	3.50±0.10	<3.46	<3.73
т	0.60±0.05	0.60±0.05	0.95±0.05	0.95±0.05	0.23±0.05	0.23±0.05
Ko	-		-	-	<2.50	<2.50
w	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
Po	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.100
10xP₀	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10
P ₁	2.00±0.05	2.00±0.05	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
Do	1.55±0.05	1.55±0.05	1.55±0.05	1.50±0.05	1.50±0.05	1.50±0.05
D ₁	-		-	-	1.00±0.10	1.00±0.10
E	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.10	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05



Size	0603, 0805, 1206, 1210								
Reel size	7"	10"	13"						
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2						
W 1	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0						
Α	178.0±0.10	250.0±1.0	330.0±1.0						
N	60.0+1.0/-0	100.0±1.0	100±1.0						



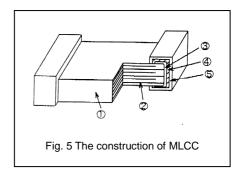
Description of customer label



- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Nan	ne	X7R, X5R, Y5V
1	Ceramic r	naterial	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

